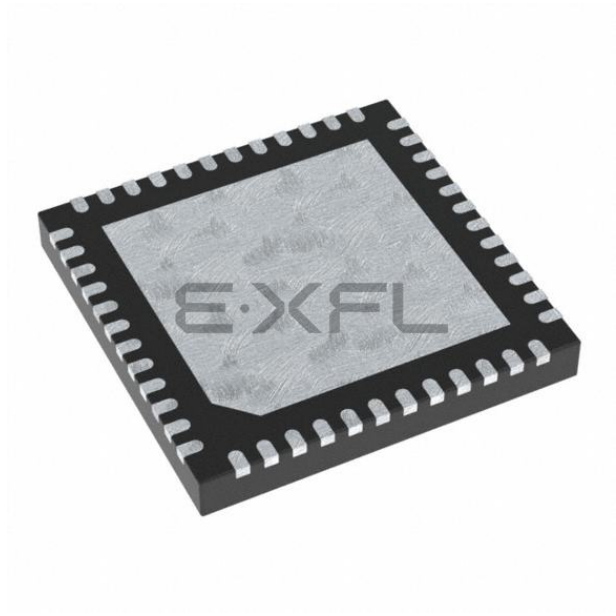

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	64MHz
Connectivity	I²C, MMC, SPI, SSC, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	34
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 8x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-VFQFN Exposed Pad
Supplier Device Package	48-QFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsam3s1ab-mu

Figure 2-3. SAM3S 48-pin Version Block Diagram

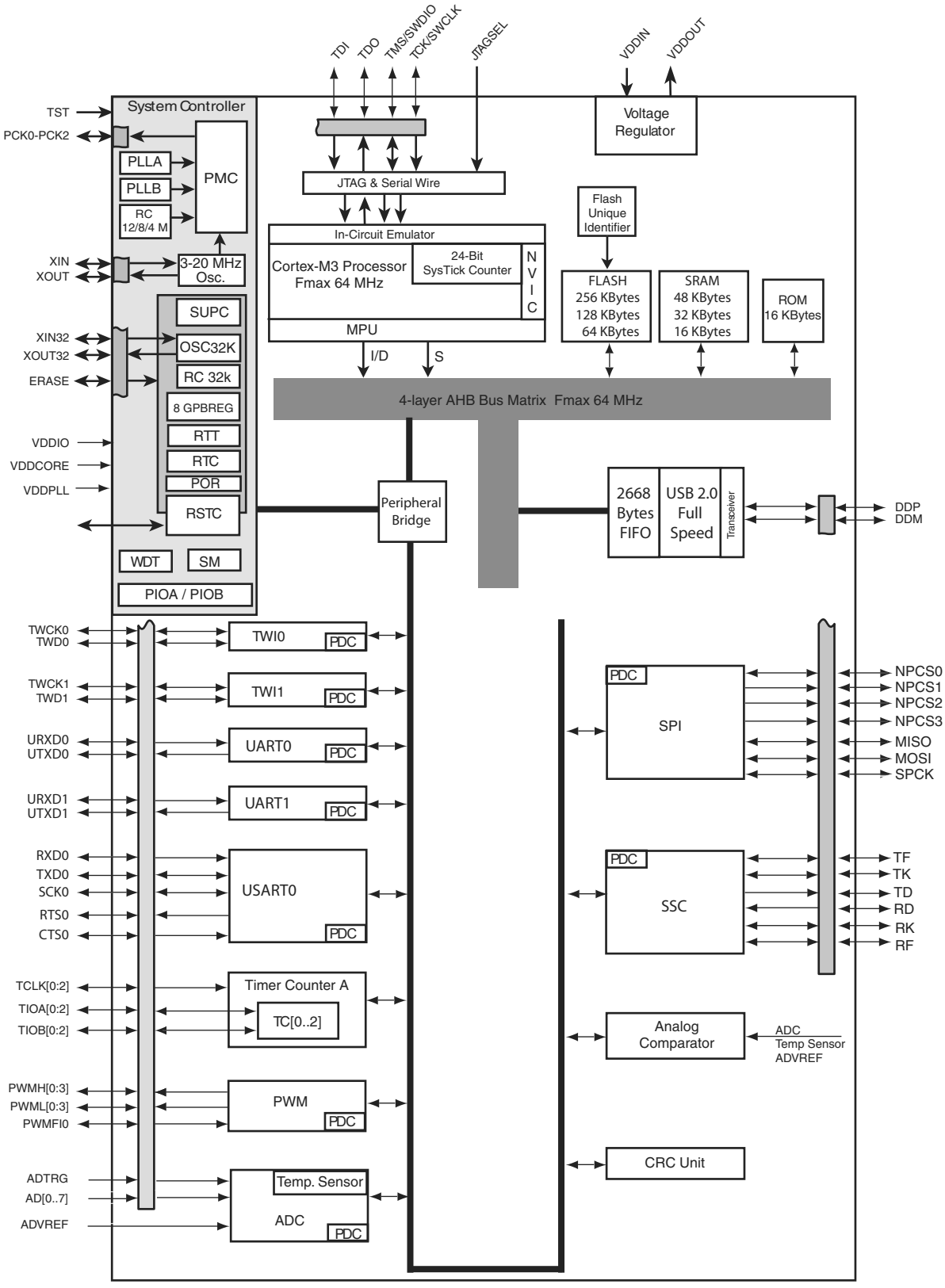


Table 3-1. Signal Description List (Continued)

Signal Name	Function	Type	Active Level	Voltage reference	Comments
Universal Asynchronous Receiver Transmitter - UARTx					
URXDx	UART Receive Data	Input			
UTXDx	UART Transmit Data	Output			
PIO Controller - PIOA - PIOB - PIOC					
PA0 - PA31	Parallel IO Controller A	I/O		VDDIO	Reset State: - PIO or System IOs(2) - Internal pull-up enabled - Schmitt Trigger enabled(1)
PB0 - PB14	Parallel IO Controller B	I/O			
PC0 - PC31	Parallel IO Controller C	I/O			
PIO Controller - Parallel Capture Mode (PIOA Only)					
PIODC0-PIODC7	Parallel Capture Mode Data	Input		VDDIO	
PIODCCLK	Parallel Capture Mode Clock	Input			
PIODCEN1-2	Parallel Capture Mode Enable	Input			
External Bus Interface					
D0 - D7	Data Bus	I/O			
A0 - A23	Address Bus	Output			
NWAIT	External Wait Signal	Input	Low		
Static Memory Controller - SMC					
NCS0 - NCS3	Chip Select Lines	Output	Low		
NRD	Read Signal	Output	Low		
NWE	Write Enable	Output	Low		
NAND Flash Logic					
NANDOE	NAND Flash Output Enable	Output	Low		
NANDWE	NAND Flash Write Enable	Output	Low		
High Speed Multimedia Card Interface - HSMCI					
MCCK	Multimedia Card Clock	I/O			
MCCDA	Multimedia Card Slot A Command	I/O			
MCDA0 - MCDA3	Multimedia Card Slot A Data	I/O			
Universal Synchronous Asynchronous Receiver Transmitter USARTx					
SCKx	USARTx Serial Clock	I/O			
TXDx	USARTx Transmit Data	I/O			
RXDx	USARTx Receive Data	Input			
RTSx	USARTx Request To Send	Output			
CTSx	USARTx Clear To Send	Input			
DTR1	USART1 Data Terminal Ready	I/O			
DSR1	USART1 Data Set Ready	Input			
DCD1	USART1 Data Carrier Detect	Input			
RI1	USART1 Ring Indicator	Input			

Table 3-1. Signal Description List (Continued)

Signal Name	Function	Type	Active Level	Voltage reference	Comments
Synchronous Serial Controller - SSC					
TD	SSC Transmit Data	Output			
RD	SSC Receive Data	Input			
TK	SSC Transmit Clock	I/O			
RK	SSC Receive Clock	I/O			
TF	SSC Transmit Frame Sync	I/O			
RF	SSC Receive Frame Sync	I/O			
Timer/Counter - TC					
TCLKx	TC Channel x External Clock Input	Input			
TIOAx	TC Channel x I/O Line A	I/O			
TIOBx	TC Channel x I/O Line B	I/O			
Pulse Width Modulation Controller- PWMC					
PWMHx	PWM Waveform Output High for channel x	Output			
PWMLx	PWM Waveform Output Low for channel x	Output			only output in complementary mode when dead time insertion is enabled
PWMFI0	**PWM Fault Input**	Input			
Serial Peripheral Interface - SPI					
MISO	Master In Slave Out	I/O			
MOSI	Master Out Slave In	I/O			
SPCK	SPI Serial Clock	I/O			
SPI_NPCS0	SPI Peripheral Chip Select 0	I/O	Low		
SPI_NPCS1 - SPI_NPCS3	SPI Peripheral Chip Select	Output	Low		
Two-Wire Interface- TWI					
TWDx	TWIx Two-wire Serial Data	I/O			
TWCKx	TWIx Two-wire Serial Clock	I/O			
Analog					
ADVREF	ADC, DAC and Analog Comparator Reference	Analog			
Analog-to-Digital Converter - ADC					
AD0 - AD14	Analog Inputs	Analog, Digital			
ADTRG	ADC Trigger	Input		VDDIO	
12-bit Digital-to-Analog Converter - DAC					
DAC0 - DAC1	Analog output	Analog, Digital			
DACTRG	DAC Trigger	Input		VDDIO	

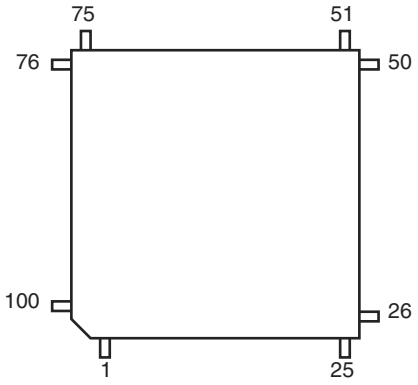
4. Package and Pinout

4.1 SAM3S4/2/1C Package and Pinout

Figure 4-2 shows the orientation of the 100-ball TFBGA Package

4.1.1 100-lead LQFP Package Outline

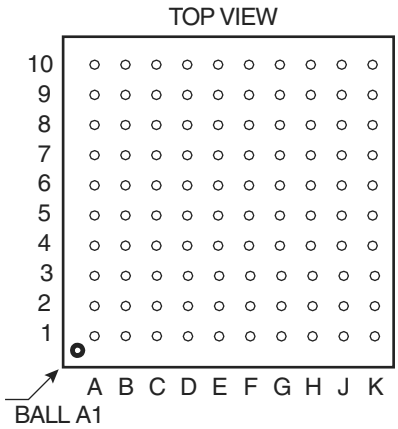
Figure 4-1. Orientation of the 100-lead LQFP Package



4.1.2 100-ball TFBGA Package Outline

The 100-Ball TFBGA package has a 0.8 mm ball pitch and respects Green Standards. Its dimensions are 9 x 9 x 1.1 mm.

Figure 4-2. Orientation of the 100-BALL TFBGA Package

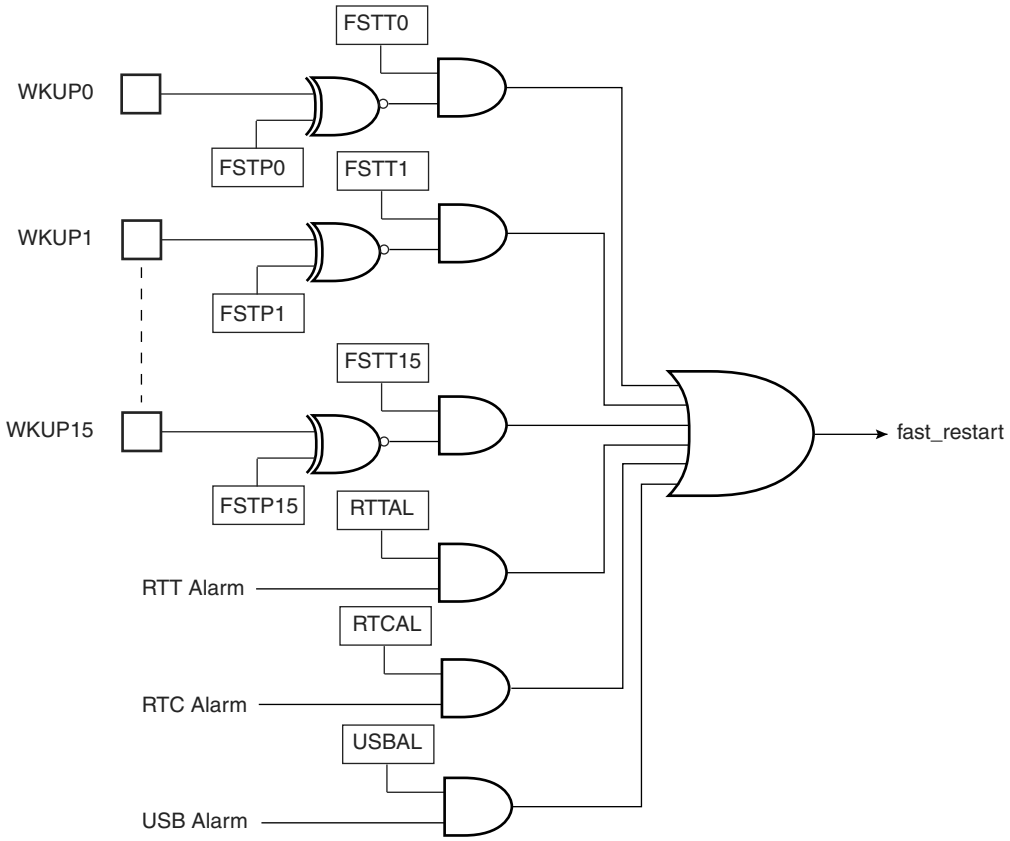


5.7 Fast Startup

The device allows the processor to restart in a few microseconds while the processor is in wait mode. A fast start up can occur upon detection of a low level on one of the 19 wake-up inputs (WKUP0 to 15 + SM + RTC + RTT).

The fast restart circuitry, as shown in Figure 5-5, is fully asynchronous and provides a fast start-up signal to the Power Management Controller. As soon as the fast start-up signal is asserted, the PMC automatically restarts the embedded 4/8/12 MHz fast RC oscillator, switches the master clock on this 4MHz clock and reenables the processor clock.

Figure 5-5. Fast Start-Up Circuitry



6. Input/Output Lines

The SAM3S has several kinds of input/output (I/O) lines such as general purpose I/Os (GPIO) and system I/Os. GPIOs can have alternate functionality due to multiplexing capabilities of the PIO controllers. The same PIO line can be used whether in IO mode or by the multiplexed peripheral. System I/Os include pins such as test pins, oscillators, erase or analog inputs.

6.1 General Purpose I/O Lines

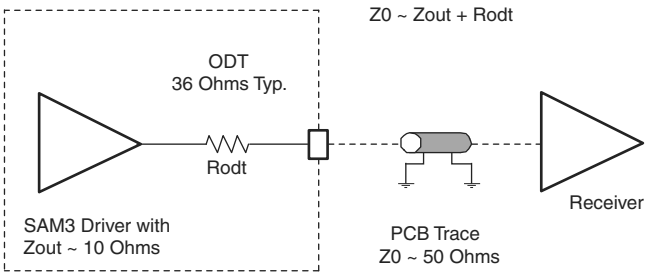
GPIO Lines are managed by PIO Controllers. All I/Os have several input or output modes such as pull-up or pull-down, input Schmitt triggers, multi-drive (open-drain), glitch filters, debouncing or input change interrupt. Programming of these modes is performed independently for each I/O line through the PIO controller user interface. For more details, refer to the product PIO controller section.

The input output buffers of the PIO lines are supplied through VDDIO power supply rail.

The SAM3S embeds high speed pads able to handle up to 32 MHz for HSMCI (MCK/2), 45 MHz for SPI clock lines and 35 MHz on other lines. See AC Characteristics Section in the Electrical Characteristics Section of the datasheet for more details. Typical pull-up and pull-down value is 100 kΩ for all I/Os.

Each I/O line also embeds an ODT (On-Die Termination), see Figure 6-1. It consists of an internal series resistor termination scheme for impedance matching between the driver output (SAM3S) and the PCB trace impedance preventing signal reflection. The series resistor helps to reduce IOs switching current (di/dt) thereby reducing in turn, EMI. It also decreases overshoot and undershoot (ringing) due to inductance of interconnect between devices or between boards. In conclusion ODT helps diminish signal integrity issues.

Figure 6-1. On-Die Termination



6.2 System I/O Lines

System I/O lines are pins used by oscillators, test mode, reset and JTAG to name but a few. Described below are the SAM3S system I/O lines shared with PIO lines:

These pins are software configurable as general purpose I/O or system pins. At startup the default function of these pins is always used.

6.4 NRST Pin

The NRST pin is bidirectional. It is handled by the on-chip reset controller and can be driven low to provide a reset signal to the external components or asserted low externally to reset the microcontroller. It will reset the Core and the peripherals except the Backup region (RTC, RTT and Supply Controller). There is no constraint on the length of the reset pulse and the reset controller can guarantee a minimum pulse length. The NRST pin integrates a permanent pull-up resistor to VDDIO of about 100 kΩ. By default, the NRST pin is configured as an input.

6.5 ERASE Pin

The ERASE pin is used to reinitialize the Flash content (and some of its NVM bits) to an erased state (all bits read as logic level 1). It integrates a pull-down resistor of about 100 kΩ to GND, so that it can be left unconnected for normal operations.

This pin is debounced by SCLK to improve the glitch tolerance. When the ERASE pin is tied high during less than 100 ms, it is not taken into account. The pin must be tied high during more than 220 ms to perform a Flash erase operation.

The ERASE pin is a system I/O pin and can be used as a standard I/O. At startup, the ERASE pin is not configured as a PIO pin. If the ERASE pin is used as a standard I/O, startup level of this pin must be low to prevent unwanted erasing. Please refer to Section 11.2 “Peripheral Signal Multiplexing on I/O Lines” on page 41. Also, if the ERASE pin is used as a standard I/O output, asserting the pin to low does not erase the Flash.

7.5 Master to Slave Access

All the Masters can normally access all the Slaves. However, some paths do not make sense, for example allowing access from the Cortex-M3 S Bus to the Internal ROM. Thus, these paths are forbidden or simply not wired and shown as “-” in the following table.

Table 7-3. SAM3S Master to Slave Access

Slaves	Masters	0	1	2	3
		Cortex-M3 I/D Bus	Cortex-M3 S Bus	PDC	CRCCU
0	Internal SRAM	-	X	X	X
1	Internal ROM	X	-	X	X
2	Internal Flash	X	-	-	X
3	External Bus Interface	-	X	X	X
4	Peripheral Bridge	-	X	X	-

7.6 Peripheral DMA Controller

- Handles data transfer between peripherals and memories
- Low bus arbitration overhead
  - One Master Clock cycle needed for a transfer from memory to peripheral
  - Two Master Clock cycles needed for a transfer from peripheral to memory
- Next Pointer management for reducing interrupt latency requirement

The Peripheral DMA Controller handles transfer requests from the channel according to the following priorities (Low to High priorities):

Table 7-4. Peripheral DMA Controller

Instance Name	Channel T/R	100 & 64 Pins	48 Pins
PWM	Transmit	x	x
TWI1	Transmit	x	x
TWI0	Transmit	x	x
UART1	Transmit	x	x
UART0	Transmit	x	x
USART1	Transmit	x	N/A
USART0	Transmit	x	x
DAC	Transmit	x	N/A
SPI	Transmit	x	x
SSC	Transmit	x	x
HSMCI	Transmit	x	N/A
PIOA	Transmit	x	x
TWI1	Receive	x	x
TWI0	Receive	x	x
UART1	Receive	x	N/A
UART0	Receive	x	x

9. Memories

9.1 Embedded Memories

9.1.1 Internal SRAM

The ATSAM3S4 product (256-Kbyte internal Flash version) embeds a total of 48 Kbytes high-speed SRAM.

The ATSAM3S2 product (128-Kbyte internal Flash version) embeds a total of 32 Kbytes high-speed SRAM.

The ATSAM3S1 product (64-Kbyte internal Flash version) embeds a total of 16 Kbytes high-speed SRAM.

The SRAM is accessible over System Cortex-M3 bus at address 0x2000 0000.

The SRAM is in the bit band region. The bit band alias region is mapped from 0x2200 0000 to 0x23FF FFFF.

9.1.2 Internal ROM

The SAM3S product embeds an Internal ROM, which contains the SAM Boot Assistant (SAM-BA), In Application Programming routines (IAP) and Fast Flash Programming Interface (FFPI).

At any time, the ROM is mapped at address 0x0080 0000.

9.1.3 Embedded Flash

9.1.3.1 Flash Overview

The Flash of the ATSAM3S4 (256-Kbytes internal Flash version) is organized in one bank of 1024 pages (Single plane) of 256 bytes.

The Flash of the ATSAM3S2 (128-Kbytes internal Flash version) is organized in one bank of 512 pages (Single plane) of 256 bytes.

The Flash of the ATSAM3S1 (64-Kbytes internal Flash version) is organized in one bank of 256 pages (Single plane) of 256 bytes.

The Flash contains a 128-byte write buffer, accessible through a 32-bit interface.

9.1.3.2 Flash Power Supply

The Flash is supplied by VDDCORE.

9.1.3.3 Enhanced Embedded Flash Controller

The Enhanced Embedded Flash Controller (EEFC) manages accesses performed by the masters of the system. It enables reading the Flash and writing the write buffer. It also contains a User Interface, mapped on the APB.

The Enhanced Embedded Flash Controller ensures the interface of the Flash block with the 32-bit internal bus. Its 128-bit wide memory interface increases performance.

The user can choose between high performance or lower current consumption by selecting either 128-bit or 64-bit access. It also manages the programming, erasing, locking and unlocking sequences of the Flash using a full set of commands.

One of the commands returns the embedded Flash descriptor definition that informs the system about the Flash organization, thus making the software generic.

9.1.3.4 Flash Speed

The user needs to set the number of wait states depending on the frequency used.

For more details, refer to the AC Characteristics sub section in the product Electrical Characteristics Section.

9.1.3.5 Lock Regions

Several lock bits used to protect write and erase operations on lock regions. A lock region is composed of several consecutive pages, and each lock region has its associated lock bit.

Table 9-1. Number of Lock Bits

Product	Number of Lock Bits	Lock Region Size
ATSAM3S4	16	16 kbytes (64 pages)
ATSAM3S2	8	16 kbytes (64 pages)
ATSAM3S1	4	16 kbytes (64 pages)

If a locked-region's erase or program command occurs, the command is aborted and the EEFC triggers an interrupt.

The lock bits are software programmable through the EEFC User Interface. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

9.1.3.6 Security Bit Feature

The SAM3S features a security bit, based on a specific General Purpose NVM bit (GPNVM bit 0). When the security is enabled, any access to the Flash, SRAM, Core Registers and Internal Peripherals either through the ICE interface or through the Fast Flash Programming Interface, is forbidden. This ensures the confidentiality of the code programmed in the Flash.

This security bit can only be enabled, through the command "Set General Purpose NVM Bit 0" of the EEFC User Interface. Disabling the security bit can only be achieved by asserting the ERASE pin at 1, and after a full Flash erase is performed. When the security bit is deactivated, all accesses to the Flash, SRAM, Core registers, Internal Peripherals are permitted.

It is important to note that the assertion of the ERASE pin should always be longer than 200 ms.

As the ERASE pin integrates a permanent pull-down, it can be left unconnected during normal operation. However, it is safer to connect it directly to GND for the final application.

9.1.3.7 Calibration Bits

NVM bits are used to calibrate the brownout detector and the voltage regulator. These bits are factory configured and cannot be changed by the user. The ERASE pin has no effect on the calibration bits.

9.1.3.8 Unique Identifier

Each device integrates its own 128-bit unique identifier. These bits are factory configured and cannot be changed by the user. The ERASE pin has no effect on the unique identifier.

9.1.3.9 Fast Flash Programming Interface

The Fast Flash Programming Interface allows programming the device through a multiplexed fully-handshaked parallel port. It allows gang programming with market-standard industrial programmers.

The FFPI supports read, page program, page erase, full erase, lock, unlock and protect commands.

The Fast Flash Programming Interface is enabled and the Fast Programming Mode is entered when TST is tied high and PA0 and PA1 are tied low.

9.1.3.10 SAM-BA® Boot

The SAM-BA Boot is a default Boot Program which provides an easy way to program in-situ the on-chip Flash memory.

The SAM-BA Boot Assistant supports serial communication via the UART and USB.

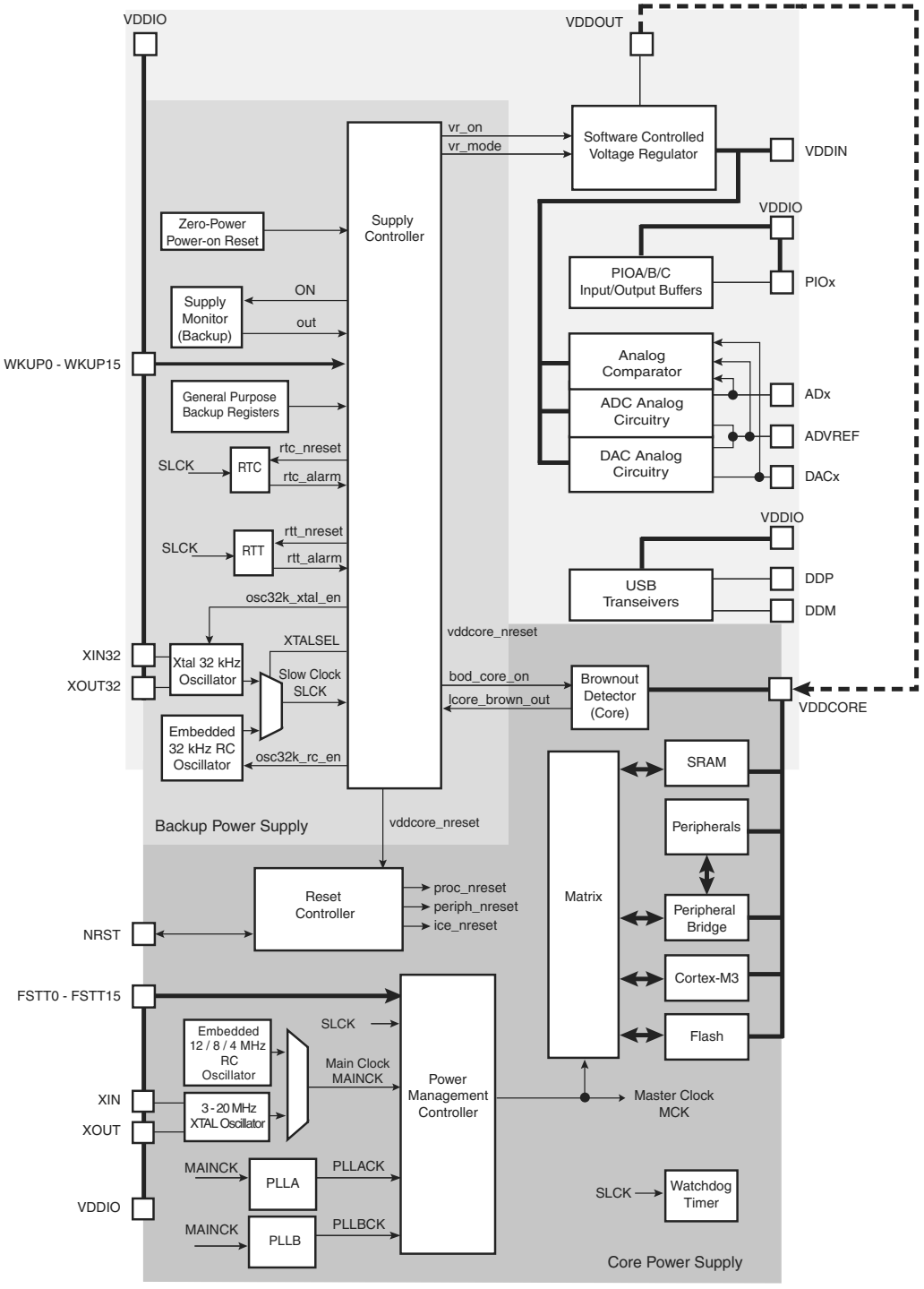
The SAM-BA Boot provides an interface with SAM-BA Graphic User Interface (GUI).

10. System Controller

The System Controller is a set of peripherals, which allow handling of key elements of the system, such as power, resets, clocks, time, interrupts, watchdog, etc...

See the system controller block diagram in Figure 10-1 on page 34.

Figure 10-1. System Controller Block Diagram



FSTT0 - FSTT15 are possible Fast Startup Sources, generated by WKUP0-WKUP15 Pins, but are not physical pins.

11.2 Peripheral Signal Multiplexing on I/O Lines

The SAM3S product features 2 PIO controllers on 48-pin and 64-pin versions (PIOA, PIOB) or 3 PIO controllers on the 100-pin version, (PIOA, PIOB, PIOC), that multiplex the I/O lines of the peripheral set.

The SAM3S 64-pin and 100-pin PIO Controllers control up to 32 lines. (See, Table 10-2.) Each line can be assigned to one of three peripheral functions: A, B or C. The multiplexing tables in the following pages define how the I/O lines of the peripherals A, B and C are multiplexed on the PIO Controllers. The column “Comments” has been inserted in this table for the user’s own comments; it may be used to track how pins are defined in an application.

Note that some peripheral functions which are output only, might be duplicated within the tables.

12.7 Pulse Width Modulation Controller (PWM)

- One Four-channel 16-bit PWM Controller, 16-bit counter per channel
- Common clock generator, providing Thirteen Different Clocks
  - A Modulo n counter providing eleven clocks
  - Two independent Linear Dividers working on modulo n counter outputs
- Independent channel programming
  - Independent Enable Disable Commands
  - Independent Clock Selection
  - Independent Period and Duty Cycle, with Double Buffering
  - Programmable selection of the output waveform polarity
  - Programmable center or left aligned output waveform
  - Independent Output Override for each channel
  - Independent complementary Outputs with 12-bit dead time generator for each channel
  - Independent Enable Disable Commands
  - Independent Clock Selection
  - Independent Period and Duty Cycle, with Double Buffering
- Synchronous Channel mode
  - Synchronous Channels share the same counter
  - Mode to update the synchronous channels registers after a programmable number of periods
- Connection to one PDC channel
  - Offers Buffer transfer without Processor Intervention, to update duty cycle of synchronous channels
- independent event lines which can send up to 4 triggers on ADC within a period
- Programmable Fault Input providing an asynchronous protection of outputs
- Stepper motor control (2 Channels)

12.8 High Speed Multimedia Card Interface (HSMCI)

- 4-bit or 1-bit Interface
- Compatibility with MultiMedia Card Specification Version 4.3
- Compatibility with SD and SDHC Memory Card Specification Version 2.0
- Compatibility with SDIO Specification Version V1.1.
- Compatibility with CE-ATA Specification 1.1
- Cards clock rate up to Master Clock divided by 2
- Boot Operation Mode support
- High Speed mode support
- Embedded power management to slow down clock rate when not used
- HSMCI has one slot supporting
  - One MultiMediaCard bus (up to 30 cards) or
  - One SD Memory Card
  - One SDIO Card
- Support for stream, block and multi-block data read and write

12.9 USB Device Port (UDP)

- USB V2.0 full-speed compliant,12 Mbits per second.
- Embedded USB V2.0 full-speed transceiver
- Embedded 2688-byte dual-port RAM for endpoints

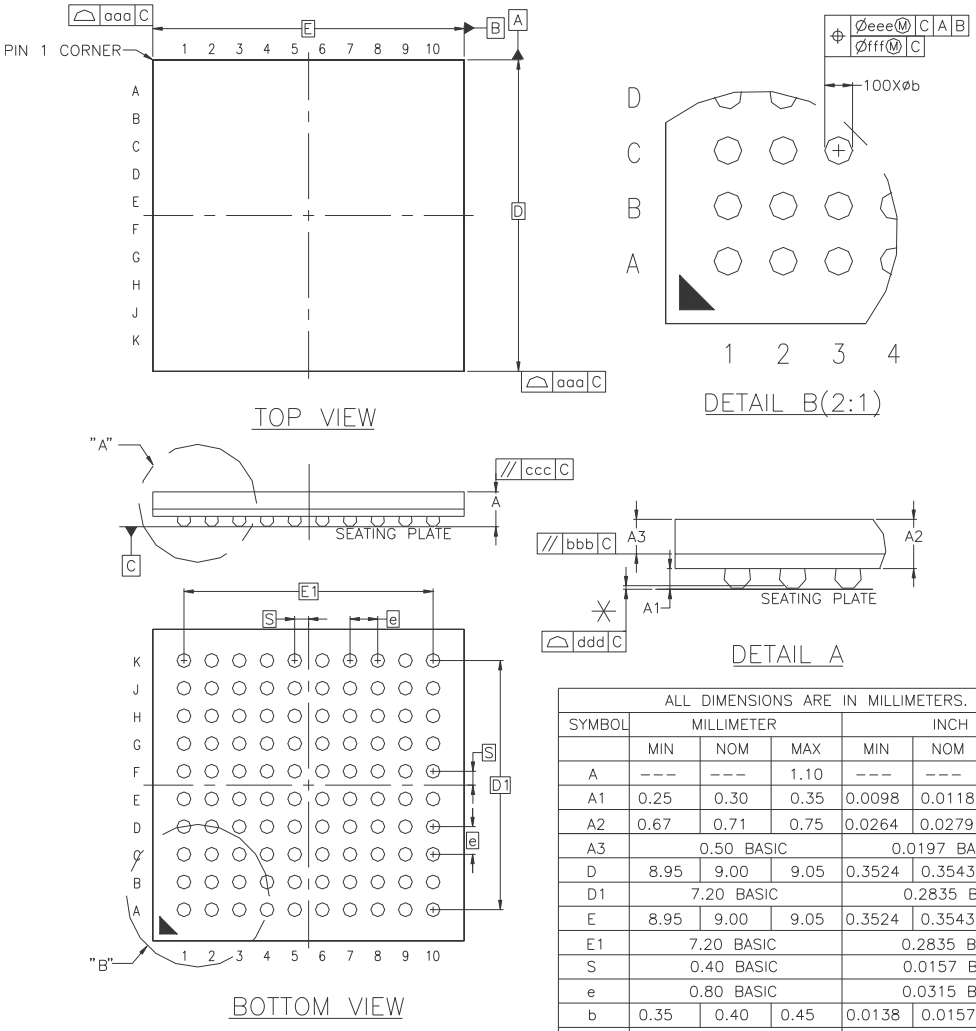
12.13 Analog Comparator

- One analog comparator
- High speed option vs. low power option
- Selectable input hysteresis:
  - 0, 20 mV, 50 mV
- Minus input selection:
  - DAC outputs
  - Temperature Sensor
  - ADVREF
  - AD0 to AD3 ADC channels
- Plus input selection:
  - All analog inputs
- output selection:
  - Internal signal
  - external pin
  - selectable inverter
- Interrupt on:
  - Rising edge, Falling edge, toggle

12.14 Cyclic Redundancy Check Calculation Unit (CRCCU)

- 32-bit cyclic redundancy check automatic calculation
- CRC calculation between two addresses of the memory

Figure 13-2. 100-ball TFBGA Package Drawing



ALL DIMENSIONS ARE IN MILLIMETERS.						
SYMBOL	MILLIMETER			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	---	---	1.10	---	---	0.0575
A1	0.25	0.30	0.35	0.0098	0.0118	0.0138
A2	0.67	0.71	0.75	0.0264	0.0279	0.0295
A3	0.50 BASIC			0.0197 BASIC		
D	8.95	9.00	9.05	0.3524	0.3543	0.3563
D1	7.20 BASIC			0.2835 BASIC		
E	8.95	9.00	9.05	0.3524	0.3543	0.3563
E1	7.20 BASIC			0.2835 BASIC		
S	0.40 BASIC			0.0157 BASIC		
e	0.80 BASIC			0.0315 BASIC		
b	0.35	0.40	0.45	0.0138	0.0157	0.0177
aaa	0.15			0.0059		
bbb	0.20			0.0079		
ccc	0.20			0.0079		
ddd	0.12			0.0047		
eee	0.15			0.0059		
fff	0.08			0.0031		

Figure 13-3. 64- and 48-lead LQFP Package Drawing

Table 13-2. 64-lead LQFP Package Dimensions (in mm)

Symbol	Millimeter			Inch		
	Min	**Nom**	**Max**	**Min**	**Nom**	**Max**
A	–	–	1.60	–	–	0.063
A1	0.05	–	0.15	0.002	–	0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
D	12.00 BSC			0.472 BSC		
D1	10.00 BSC			0.383 BSC		
E	12.00 BSC			0.472 BSC		
E1	10.00 BSC			0.383 BSC		
R2	0.08	–	0.20	0.003	–	0.008
R1	0.08	–	–	0.003	–	–
q	0°	3.5°	7°	0°	3.5°	7°
θ_1	0°	–	–	0°	–	–
θ_2	11°	12°	13°	11°	12°	13°
θ_3	11°	12°	13°	11°	12°	13°
c	0.09	–	0.20	0.004	–	0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	1.00 REF			0.039 REF		
S	0.20	–	–	0.008	–	–
b	0.17	0.20	0.27	0.007	0.008	0.011
e	0.50 BSC.			0.020 BSC.		
D2	7.50			0.285		
E2	7.50			0.285		
Tolerances of Form and Position						
aaa	0.20			0.008		
bbb	0.20			0.008		
ccc	0.08			0.003		
ddd	0.08			0.003		

Table 13-3. 48-pad QFN Package Dimensions (in mm)

Symbol	Millimeter			Inch		
	Min	**Nom**	**Max**	**Min**	**Nom**	**Max**
A	–	–	090	–	–	0.035
A1	–	–	0.050	–	–	0.002
A2	–	0.65	0.70	–	0.026	0.028
A3	0.20 REF			0.008 REF		
b	0.18	0.20	0.23	0.007	0.008	0.009
D	7.00 bsc			0.276 bsc		
D2	5.45	5.60	5.75	0.215	0.220	0.226
E	7.00 bsc			0.276 bsc		
E2	5.45	5.60	5.75	0.215	0.220	0.226
L	0.35	0.40	0.45	0.014	0.016	0.018
e	0.50 bsc			0.020 bsc		
R	0.09	–	–	0.004	–	–
Tolerances of Form and Position						
aaa	0.10			0.004		
bbb	0.10			0.004		
ccc	0.05			0.002		

Revision History

Doc. Rev	Comments	Change Request Ref.
6500ES	Section 1. “Features”updated, “Low Power Modes” , Sleep and Backup modes, down to 1.8 µA in Backup mode	rfo
	Figure 8-1, "SAM3S Product Mapping", SRAM associated 1 MByte bit band region mapping changed: 0x22000000 to 0x23FFFFFF.	
	Document format updated, subsequently pagination changed	
	Section 14. “Ordering Information” Introduced MRL B for SAM3S1 parts..	8545
6500DS	Replace all mention to 100-ball LFBGA into 100-ball TFBGA.	8044
	Add table note 5 in Table 3-1, “Signal Description List”.	7632
	Add MOSCRCEN bit details in Section 5.5.2 “Wait Mode”.	7639
	Section 9.1.3.9 “Fast Flash Programming Interface” updated.	7668-7901
	Notes under Figure 5-1, "Single Supply" and Figure 5-2, "Core Externally Supplied" modified.	7887
	Cross-References (1) added for 64-pin packages in table Table 1-1, “Configuration Summary”.	8033
	Pin 22 value changed for PA23/PGMD11 in Table 4-1, “100-lead LQFP SAM3S4/2/1C Pinout”.	8093
	"High Frequency Asynchronous clocking mode" removed from Section 12.7 “Pulse Width Modulation Controller (PWM)”	8095
	“Write Protected Registers” added in “Description” , in Peripherals list.	8213
	ADC column values updated in Table 1-1, “Configuration Summary”.	rfo
6500CS	Missing PGMD8 to 15 added to Table 4-1, “100-lead LQFP SAM3S4/2/1C Pinout” and Table 4-2, “100-ball TFBGA SAM3S4/2/1C Pinout”.	rfo
	Section 5.7 “Fast Startup” updated.	
	Typo fixed on back page: ‘techincal’ --> ‘technical’.	7536
	Typos fixed in Section 1. “Features”.	7524
	Missing title added to Table 14-1.	
	PLLA input frequency range updated in Section 10.5 “Clock Generator”.	7494
	A sentence completed in Section 5.5.2 “Wait Mode”.	7492
	Last sentence removed from Section 9.1.3.10 “SAM-BA® Boot”.	7428
	‘three GPNVM bits’ replaced by ‘two GPNVM bits’ in Section 9.1.3.11 “GPNVM Bits”.	
	Leftover sentence removed from Section 4.1 “SAM3S4/2/1C Package and Pinout”.	7394
6500BS	“Packages” on page 2, package size or pitch updated.	
	Table 1-1, “Configuration Summary”, ADC column updated, footnote gives precision on reserved channel.	7214
	Table 4-2, “100-ball TFBGA SAM3S4/2/1C Pinout”, pinout information is available.	6981
	Figure 5-1, "Single Supply",Figure 5-2, "Core Externally Supplied" , updated notes below figures.	7201
	Figure 5-2, "Core Externally Supplied", Figure 5-3, "Backup Battery", ADC, DAC, Analog Comparator supply is 2.0V-3.6V.	7243/rfo
	Section 12.13 “Analog Comparator”, “Peripherals” on page 2, reference to “window function” removed.	7103
	Section 9.1.3.8 “Unique Identifier”, Each device integrates its own 128-bit unique identifier.	7307
6500AS	First issue	

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